



晶方半导体科技（苏州）有限公司
China Wafer Level CSP Ltd.

	Position	Name	Date
Prepared by	Design Eng.	Ivy	17-Dec-2007
Checked by	Design Eng.	Linda	17-Dec-2007
Approved by	VP QRA	Asher	17-Dec-2007

Layout for PixelPlus PO6030K device using ShellOC Technology (Rev.3)

Customer Product ID:

PO6030k

ShellOC Package Dimensions:

	Symbol	Nominal	Min	Max	Nominal	Min	Max
			Millimeters			Inches	
Package Body Dimension X	A	3.270	3.245	3.295	0.12874	0.12776	0.12972
Package Body Dimension Y	B	4.100	4.075	4.125	0.16142	0.16043	0.16240
Package Height	C	0.867	0.807	0.927	0.03413	0.03177	0.03650
Thickness from top glass surface to wafer	C3	0.435	0.415	0.455	0.01713	0.01634	0.01791
Package Body Thickness	C2	0.737	0.692	0.782	0.02902	0.02724	0.03079
Ball Height	C1	0.130	0.100	0.160	0.00512	0.00394	0.00630
Ball Diameter	D	0.250	0.220	0.280	0.00984	0.00866	0.01102
Total Ball Count	N	25					
Ball Count X axis	N1	5					
Ball Count Yaxis	N2	6					
Pins Pitch X axis	J1	0.600					
Pins Pitch Y axis	J2	0.600					
Edge to Ball Center Distance along X	S1	0.435	0.405	0.465	0.01713	0.01594	0.01831
Edge to Ball Center Distance along Y	S2	0.550	0.520	0.580	0.02165	0.02047	0.02283

Table 1

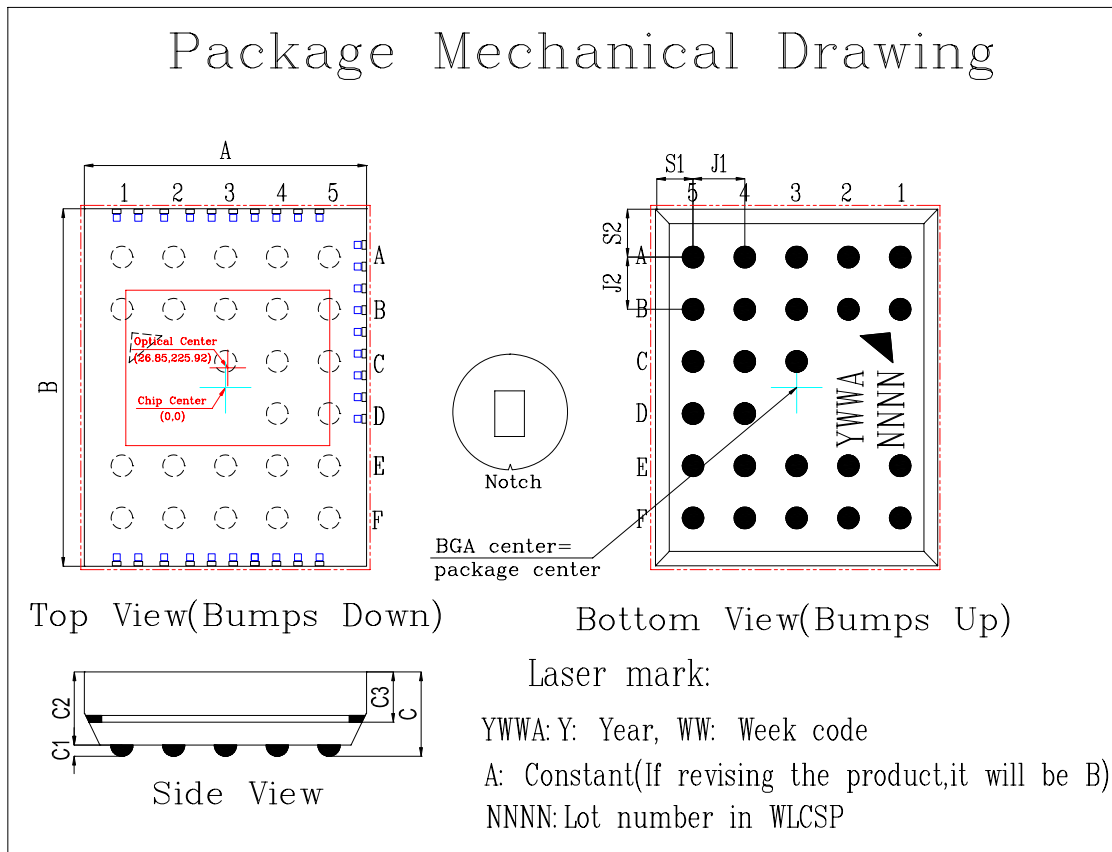


Figure 1



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Ball Matrix Table(see Fig.1)

Table2

	1	2	3	4	5
A	AVDD	Reset-B	VSYNC	D6	DGND
B	AGND	Standby	D7	HSYNC	D5
C			HVDD	D4	D3
D				D2	D1
E	AGND1	SDAT	DVDD	DGND	D0
F	AVDD1	TestEn	SClk	MCLK	PCLK

Table2

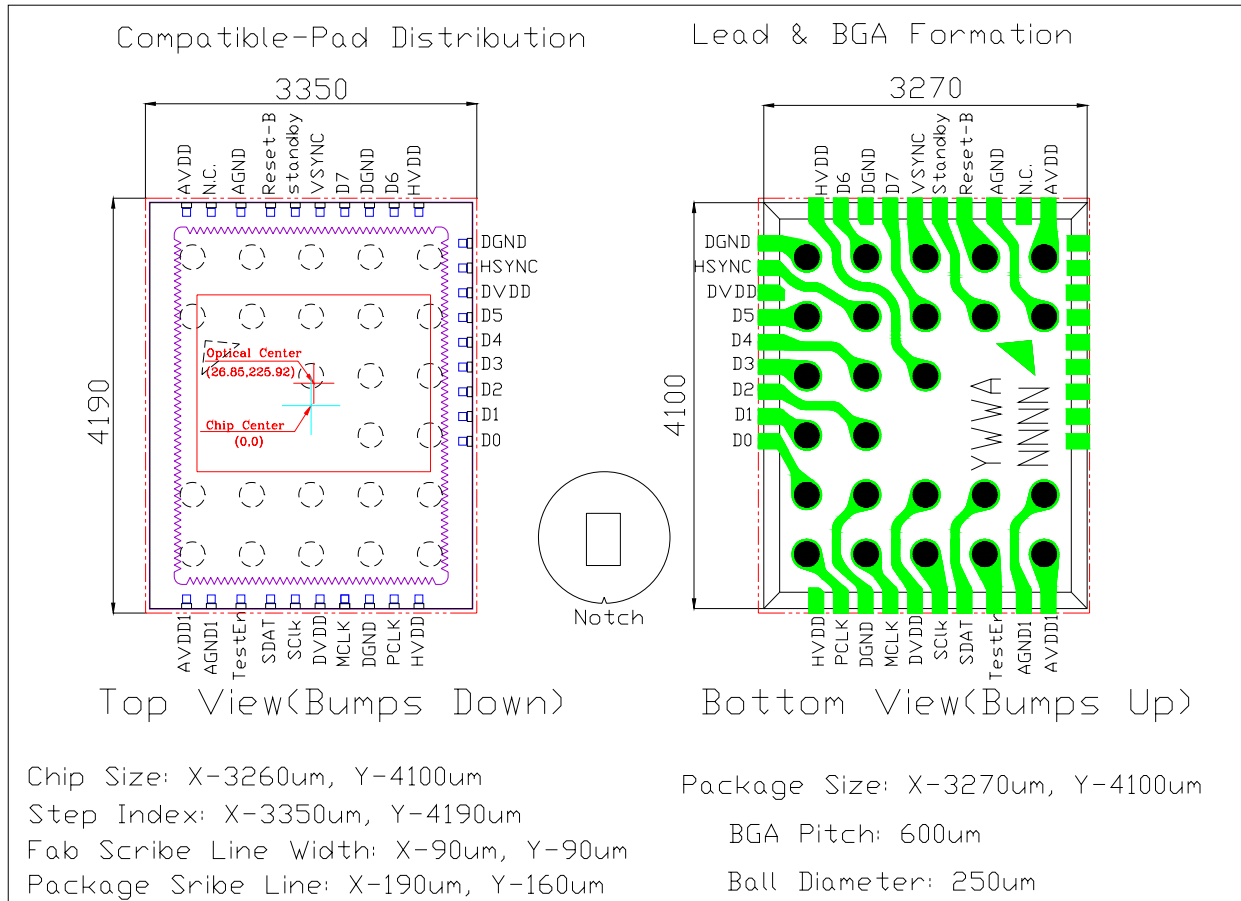


Figure 2

Notch orientation (with reference to Pad Extension Formation view on figure #2)	Up	Down	Right	Left	Other
			X		

Table 3



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Description of change:

Revision	Date	Item	Was:	Is:	Comments:
Rev.1	29.Oct.07	New Release			ShellOC Process
Rev.2	11.Dec.07	B	4.11 mm	4.10 mm	Changes due to PixelPlus incorrect design that does not comply with Shellcase design rules.
		C	0.877 mm	0.867 mm	
		C3	0.445 mm	0.435 mm	
		C2	0.747 mm	0.737 mm	
		S1	0.435 mm	0.420 mm	
		S2	0.555mm	0.550mm	
Rev.3	12.Dec.07	S1	0.420mm	0.435mm	BGA layout changed. Requested by customer.

Layout approval by customer:

I have received and checked the proposed data sheet and package layout for our device and agree that the design was performed according to our request.

Signature: _____ Date: _____